

L Number	Hits	Search Text	DB	Time stamp
-	2	semiconductor ADJ device with wait ADJ time	USPAT	2004/05/24 16:02
-	37	semiconductor with wait ADJ time	USPAT	2004/05/24 16:02
-	109	semiconductor with wait\$3 ADJ time	USPAT	2004/05/24 16:02
-	109	semiconductor with wait\$3 ADJ time	USPAT	2004/05/24 16:04
-	593	semiconductor ADJ device AND wait\$3 ADJ time	USPAT	2004/05/24 16:04
-	6	semiconductor ADJ device AND wait\$3 ADJ time with elapse	USPAT	2004/05/24 16:07
-	0	714/815.ccls. and semiconductor ADJ device AND wait\$3 ADJ time with elapse	USPAT	2004/05/24 16:08
-	1	714/815.ccls. and semiconductor ADJ device AND wait\$3 ADJ time	USPAT	2004/05/24 16:08
-	196	714/815.ccls.	USPAT	2004/05/24 16:09
-	40	714/815.ccls. and (wait or delay) adj tim\$3	USPAT	2004/05/24 16:35
-	5	714/815.ccls. and (wait or delay) adj tim\$3 with measur\$5	USPAT	2004/05/24 16:37
-	1	714/815.ccls. and (wait or idle) adj tim\$3 with measur\$5	USPAT	2004/05/24 16:37
-	6	714/815.ccls. and wait adj tim\$3	USPAT	2004/05/24 16:41
-	287	714/\$.ccls. and wait adj tim\$3	USPAT	2004/05/24 16:41
-	287	714/\$.ccls. and wait adj tim\$3	USPAT	2004/05/24 16:44
-	3	714/\$.ccls. and wait adj tim\$3 with measur\$5	USPAT	2004/05/24 16:44
-	27	714/\$.ccls. and wait adj tim\$3 with test\$3	USPAT	2004/05/24 16:47
-	0	714/\$.ccls. and taet adj pattern and wait adj tim\$3	USPAT	2004/05/24 16:47
-	19	714/\$.ccls. and test adj pattern and wait adj tim\$3	USPAT	2004/05/24 16:57
-	188	714/\$.ccls. and test adj pattern and wait\$ with tim\$3	USPAT	2004/05/24 16:58
-	25	714/\$.ccls. and test adj pattern and wait\$ with tim\$3 and device adj under adj test	USPAT	2004/05/24 17:50
-	160	714/\$.ccls. and test adj pattern and (wait\$ or delay) with tim\$3 and device adj under adj test	USPAT	2004/05/24 18:11
-	31	714/\$.ccls. and test adj pattern and (wait\$ or delay) with tim\$3 with compar\$4 and device adj under adj test	USPAT	2004/05/24 18:10
-	0	714/\$.ccls. and test adj pattern and variable ADJ time ADJ delay and device adj under adj test	USPAT	2004/05/24 18:12
-	1	714/\$.ccls. and test adj pattern and variable ADJ time ADJ delay	USPAT	2004/05/24 18:13
-	0	714/\$.ccls. and test adj pattern and variable ADJ wait\$3 ADJ time	USPAT	2004/05/24 18:13
-	0	714/\$.ccls. and test adj pattern and adjustable with wait\$3 ADJ time	USPAT	2004/05/24 18:13
-	0	714/\$.ccls. and test adj pattern and adjust\$3 with wait\$3 adj (tim\$3 or period)	USPAT	2004/05/24 18:14
-	6	714/\$.ccls. and test adj pattern with wait\$3 adj (tim\$3 or period)	USPAT	2004/05/24 18:16
-	17	714/\$.ccls. and test adj pattern with wait\$3 with (tim\$3 or period)	USPAT	2004/05/24 18:28
-	0	"20020100000"	USPAT	2004/05/24 18:28
-	1	"20020100000"	USPAT; US-PGPUB	2004/05/24 18:28

-	383	TOSHIBA.as. and wait\$3 adj tim\$3	USPAT	2004/05/24 18:43
-	28175	TOSHIBA.as. and wait\$3 adj tim\$3 and test adj pattern and deviceADJ under adj test	USPAT	2004/05/24 18:42
-	0	TOSHIBA.as. and wait\$3 adj tim\$3 and test adj pattern and device ADJ under adj test	USPAT	2004/05/24 18:43
-	1	TOSHIBA.as. and wait\$3 adj tim\$3 and device ADJ under adj test	USPAT	2004/05/24 18:43
-	0	TOSHIBA.as. and wait\$3 adj tim\$3 with semiconductor adj test\$3	USPAT	2004/05/24 18:44
-	0	TOSHIBA.as. and wait\$3 adj tim\$3 and semiconductor adj test\$3	USPAT	2004/05/24 18:46
-	1	JP08247817	USPAT; EPO; JPO; DERWENT	2004/05/25 07:50
-	1	JP08247817	USPAT; EPO; JPO; DERWENT	2004/05/25 07:50
-	1	measurement with adjust\$4 with operating with speed and TESTING with SEMICONDUCTOR near DEVICE	USPAT	2004/05/25 07:52
-	1	measurement with adjust\$4 with speed and TESTING with SEMICONDUCTOR near DEVICE	USPAT	2004/05/25 07:53
-	19	adjust\$4 with speed and TESTING with SEMICONDUCTOR near DEVICE	USPAT	2004/05/25 07:57
-	36	adjust\$4 with time with delay and TESTING with SEMICONDUCTOR near DEVICE	USPAT	2004/05/25 07:57
-	34	714/815.ccls. and (wait or delay) adj time	USPAT	2004/05/25 15:59